

IGBT

FGA25N120AN

General Description

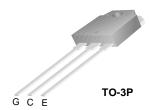
Employing NPT technology, Fairchild's AN series of IGBTs provides low conduction and switching losses. The AN series offers an solution for application such as induction heating (IH), motor control, general purpose inverters and uninterruptible power supplies (UPS).

Features

- High speed switching
- Low saturation voltage : $V_{CE(sat)} = 2.5 \text{ V } @ I_{C} = 25 \text{A}$
- · High input impedance

Applications

Induction Heating, UPS, AC & DC motor controls and general purpose inverters.





Absolute Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Description		FGA25N120AN	Units
V _{CES}	Collector-Emitter Voltage		1200	V
V _{GES}	Gate-Emitter Voltage		± 20	V
1	Collector Current	@ T _C = 25°C	40	A
IC	Collector Current	@ T _C = 100°C	25	A
I _{CM (1)}	Pulsed Collector Current		75	Α
P _D	Maximum Power Dissipation	@ T _C = 25°C	310	W
	Maximum Power Dissipation	@ T _C = 100°C	125	W
TJ	Operating Junction Temperature		-55 to +150	°C
T _{stg}	Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

Notes :

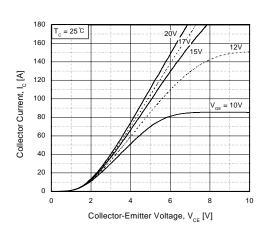
(1) Repetitive rating : Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

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Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Char	racteristics					
BV _{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V$, $I_C = 3mA$	1200			V
ΔB _{VCES} / ΔΤ _J	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V$, $I_C = 3mA$		0.6		V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			3	mΑ
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Char	acteristics					
V _{GE(th)}	G-E Threshold Voltage	$I_C = 25$ mA, $V_{CE} = V_{GE}$	3.5	5.5	7.5	V
VGE(th)	G-L Threshold Voltage	$I_C = 25A$, $V_{GE} = 15V$		2.5	3.2	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	$I_C = 25A$, $V_{GE} = 15V$, $T_C = 125^{\circ}C$		2.9		V
	Catalanan vanage	$I_C = 40A$, $V_{GE} = 15V$		3.1		V
Dynamic C _{ies}	C Characteristics Input Capacitance	$V_{CE} = 30V_{V_{GE}} = 0V_{V_{CE}}$		2100		pF
C _{oes}	Output Capacitance	$v_{CE} = 30v_{,} v_{GE} = 0v_{,}$ f = 1MHz		180		pF
C _{res}	Reverse Transfer Capacitance	1 - 1101112		90		pF
Switchir t _{d(on)}	ng Characteristics Turn-On Delay Time			60		ns
t _r	Rise Time	-		60		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 600 \text{ V}, I_{C} = 25\text{A},$		170		ns
t _f	Fall Time	$R_G = 10\Omega$, $V_{GE} = 15V$,		45	90	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C		4.8	7.2	mJ
E _{off}	Turn-Off Switching Loss			1.0	1.5	mJ
E _{ts}	Total Switching Loss	1		5.7	8.7	mJ
t _{d(on)}	Turn-On Delay Time			60		ns
t _r	Rise Time			60		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 600 \text{ V}, I_{C} = 25\text{A},$		180		ns
t _f	Fall Time	$R_G = 10\Omega, V_{GE} = 15V,$		70		ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 125°C		5.5		mJ
E _{off}	Turn-Off Switching Loss	1		1.4		mJ
E _{ts}	Total Switching Loss	1		6.9		mJ
Q_g	Total Gate Charge	V 000 V I 054		200	300	nC
Q _{ge}	Gate-Emitter Charge	$V_{CE} = 600 \text{ V}, I_{C} = 25\text{A},$		15	23	nC
Q _{gc}	Gate-Collector Charge	V _{GE} = 15V		105	160	nC
	Internal Emitter Inductance	Measured 5mm from PKG		14		nH



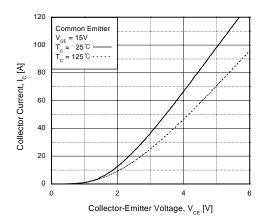
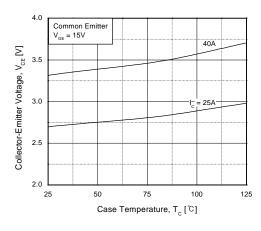


Fig 1. Typical Output Characteristics

Fig 2. Typical Saturation Voltage Characteristics



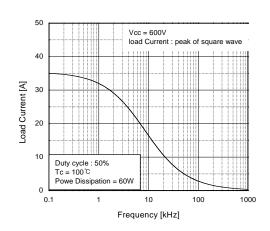
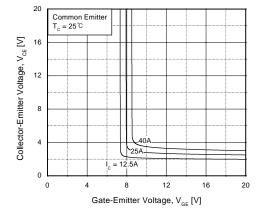


Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

Fig 4. Load Current vs. Frequency



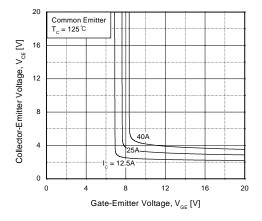
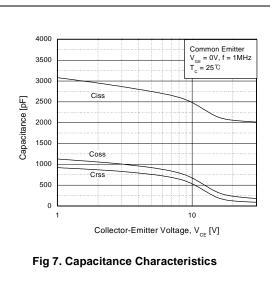


Fig 5. Saturation Voltage vs. V_{GE}

Fig 6. Saturation Voltage vs. V_{GE}

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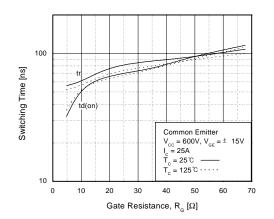
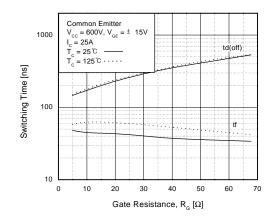


Fig 8. Turn-On Characteristics vs. Gate Resistance



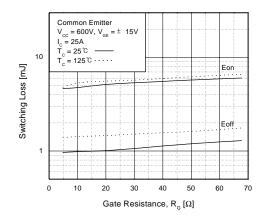
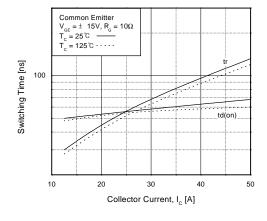


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

Fig 10. Switching Loss vs. Gate Resistance



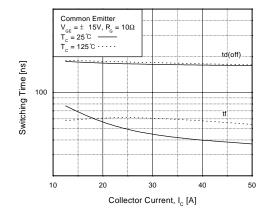
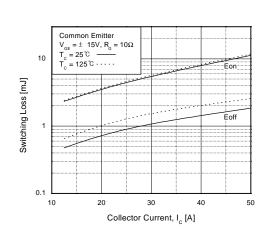


Fig 11. Turn-On Characteristics vs. Collector Current

Fig 12. Turn-Off Characteristics vs.
Collector Current

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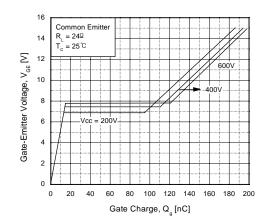
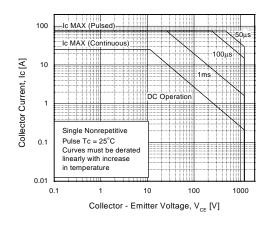


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



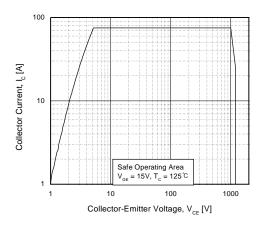


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA

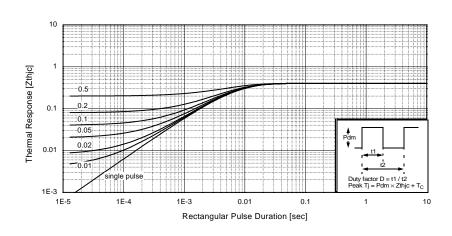
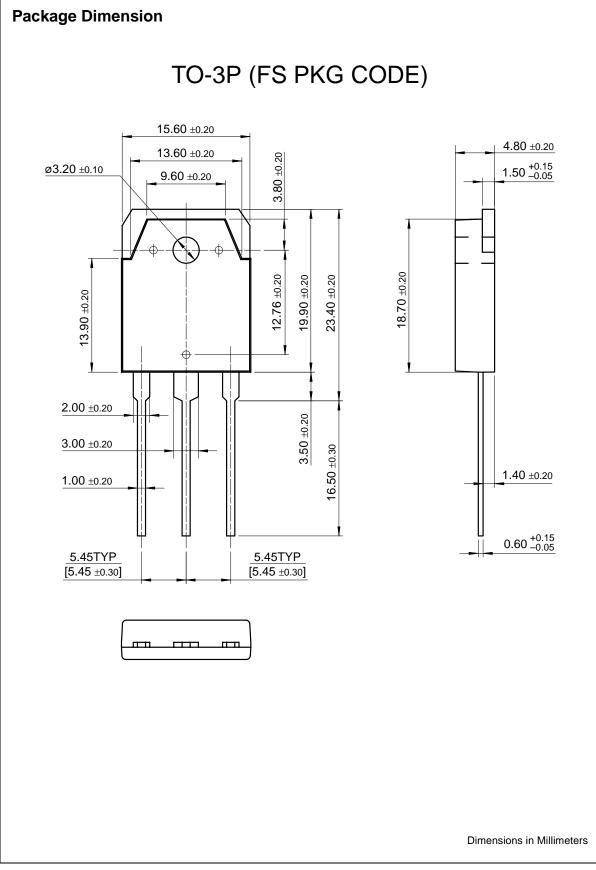


Fig 17. Transient Thermal Impedance of IGBT

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